

DuPont Kalrez® 9300

For Semiconductor Dielectric Etch Applications

Technical Information March, 2017

Product Description

DuPont® Kalrez® 9300 perfluoropolyether parts are a proven product for Dielectric (Die) Etch applications. It has been specifically designed for use in applications where the plasma environment is a combination of ions ("physical") and radicals ("chemical"), i.e., where a balance of "physical" and "chemical" plasma erosion resistance is typically required.

Kalrez® 9300 exhibits excellent resistance to oxygen and fluorine based plasma and etch process chemistry. It also offers very low metal content, excellent thermal stability and mechanical strength, and is well suited for both static and dynamic sealing applications. A maximum application temperature of 300°C (572°F) is suggested. Ultrasonic post-cleaning and packaging is standard for all Kalrez® 9300 parts.



Kalrez 9300 parts are tested on a proprietary chemistry and mechanical performance system which is not available from DuPont.

Features/Benefits

- Low erosion rate and ultra-low particle generation in localized fluorine oxygen and fluorine based (DIE) Etch
- Excellent resistance to etch process chemistry
- Very low metal content
- Excellent thermal stability
- Excellent mechanical strength

Suggested Applications

- Gas isolation seals
- Chamber fit seals
- Isolation valve seals
- Bonded gate valves/die valve clear seals

Typical Physical Properties*

Color	Brown
Hardness, Shore B (Plat Seal)	77
Hardness, Shore D (Clamp)	60
100% Modulus, MPa (psi)	4.12 (592)
Tensile Strength at Break†, MPa (psi)	14.43 (2086)
Elongation at Break†, %	230
Compression Set†, %	
70% at 200 °C (392°F)	25
70% at 250 °C (482°F)	37
70% at 300 °C (572°F)	50
Maximum Application Temperature†, °C (°F)	300 (572)

*See the specific application program.
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